

5/3,AB,LS/1 (Item 1 from file: 347)
DIALOG(R)File 347:JAPIO
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MANUFACTURE OF MULTILAYER PRINTED INTERCONNECTION BOARD

PUB. NO.: 62-287696 A]
PUBLISHED: December 14, 1987 (19871214)
INVENTOR(s): HONDA KAZUO
APPLICANT(s): NEC CORP [000423] (A Japanese Company or Corporation), JP
(Japan)
APPL. NO.: 61-131384 [JP 86131384]
FILED: June 05, 1986 (19860605)

5/3,AB,LS/2 (Item 1 from file: 351)
DIALOG(R)File 351:Derwent WPI
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WPI Acc No: 1988-026074/ 198804

Multilayer printed wire substrate mfr. - fixing wiring plate w.r.t. pin
and through hole NoAbstract Dwg 3/5

Patent Assignee: NEC CORP (NIDE)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 62287696	A	19871214	JP 86131384	A	19860605	198804 B

Priority Applications (No Type Date): JP 86131384 A 19860605

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 62287696	A		4		

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Acc no: 8014695

Basic Patent (No,Kind,Date): JP 62287696 A2 871214

<No. of Patents: 001>

MANUFACTURE OF MULTILAYER PRINTED INTERCONNECTION BOARD (English)

Patent Assignee: NIPPON ELECTRIC CO

Author (Inventor): HONDA KAZUO

IPC: *H05K-003/46;

Derwent WPI Acc No: G 88-026074

Language of Document: Japanese

Patent Family:

Patent No	Kind	Date	Applic No	Kind	Date
JP 62287696	A2	871214	JP 86131384	A	860605 (BASIC)

Priority (No,Kind,Date): JP 86131384 A 860605